L Number	Hits	Search Text	DB	Time stamp
—	131	"5374564"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/25 14:32
—	131	"5374564"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/25 14:32
—	3	("4717683" | "5196355" | "5374564").PN.	USPAT	2002/07/25 14:38
—	42	5494835.URPN.	USPAT	2002/07/25 16:32
—	401	438/455.CCLS.	USPAT	2002/07/25 16:42
—	262	438/457-458.CCLS.	USPAT	2002/07/25 16:42
—	446	438/977.CCLS.	USPAT	2002/07/25 16:43
—	181	438/977.CCLS. and (substrate with (bond$3 or laminat$3))	USPAT	2002/07/25 16:44
—	0	438/977.CCLS. and (substrate with (bond$3 or laminat$3)) and (hytrogen with (implant$3 or implantation))	USPAT	2002/07/25 16:45
—	16	438/977.CCLS. and (substrate with (bond$3 or laminat$3)) and (hydrogen with (implant$3 or implantation))	USPAT	2002/07/25 16:46
—	75	438/455-458.CCLS. and (substrate with (bond$3 or laminat$3)) and (hydrogen with (implant$3 or implantation))	USPAT	2002/07/25 16:50
—	76	438/455-458.CCLS. and (substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation))	USPAT	2002/07/25 16:52
—	1	(438/455-458.CCLS. and (substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation))) not (438/455-458.CCLS. and (substrate with (bond$3 or laminat$3)) and (hydrogen with (implant$3 or implantation)))	USPAT	2002/07/25 16:51
—	32	438/459.CCLS. and (substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation))	USPAT	2002/07/25 16:54
—	10	(438/459.CCLS. and (substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub.2") with (implant$3 or implantation))) not (438/455-458.CCLS. and (substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation)))	USPAT	2002/07/25 16:52
—	3	438/464.CCLS. and (substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation))	USPAT	2002/07/25 16:54
—	6	438/766.CCLS. and (substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation))	USPAT	2002/07/25 16:55
—	15	(438/766, 479, 517, 976, "978").CCLS. and (substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation))	USPAT	2002/07/25 16:56

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—	273	(substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation))	USPAT	2002/07/25 17:12
—	182	((substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation))) and (glass$2 or quartz)	USPAT	2002/07/25 16:57
—	97	((substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation))) and (glass$2 and quartz)	USPAT	2002/07/25 17:11
—	70	((substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation))) and (glass$2 near4 quartz)	USPAT	2002/07/25 16:59
—	0	jp2000315822$3	USPAT	2002/07/25 17:15
—	0	jp2000-315822$3	USPAT	2002/07/25 17:11
—	0	jp-2000315822$3	USPAT	2002/07/25 17:11
—	0	2000315822$3	USPAT	2002/07/25 17:11
—	0	2000-315822$3	USPAT	2002/07/25 17:11
—	1	jp2000315822$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/25 17:16
—	0	jp2000-315822$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/25 17:16
—	2	2000-315822$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/25 17:17
—	104	((substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation))) and (glass$2 near4 quartz)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/25 17:18
—	34	(((substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation))) and (glass$2 near4 quartz)) not (((substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation))) and (glass$2 near4 quartz))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/25 17:18
—	421	(substrate with (bond$3 or laminat$3)) and ((hydrogen or H2 or "H.sub. 2" or "H.sub.2") with (implant$3 or implantation))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/25 17:19